

Chip Resistor Array  
Type RCA

△ Features

- Suitable for lead free soldering
- compatible with flow and reflow soldering

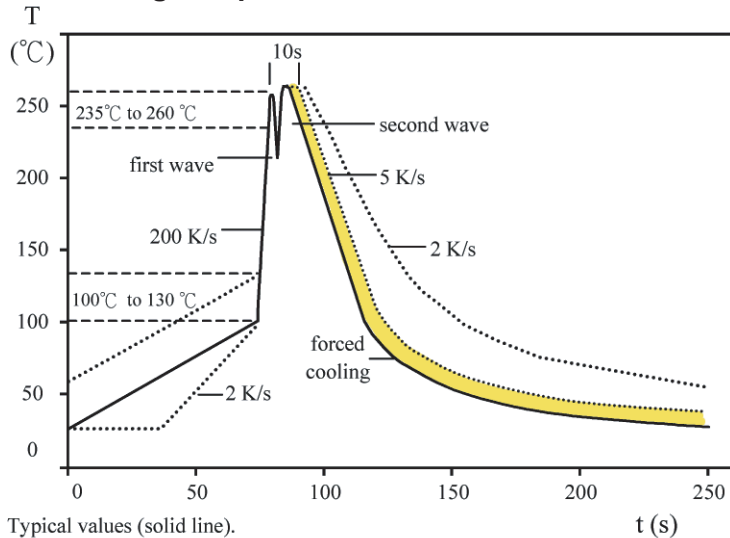
△ Applications

- Automotive, Medical, and Telecom Industries

△ Part Number

Type	Size	Isolated	Circuit Configuration	Packaging	Tolerance	Resistor Value
RCA	1206	B	8	T	J	103
	Chip Size	Isolated	Circuit 8P/4R	Taping	Example J=5% F=1%	Example 102=1KΩ 103=10KΩ

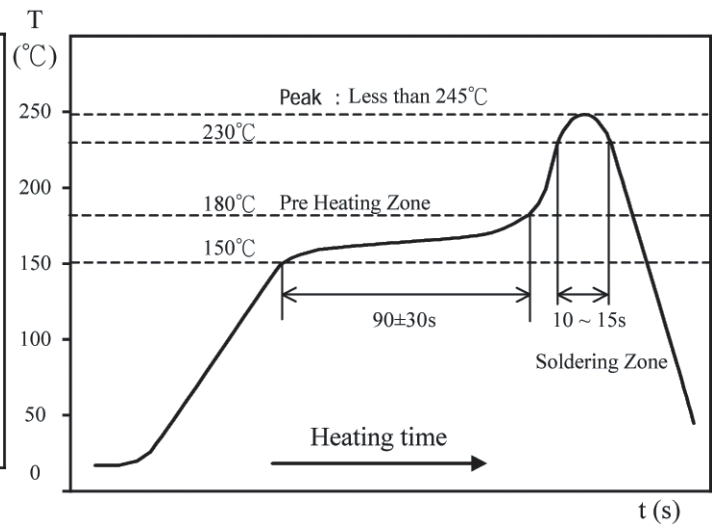
△ Soldering Temperature Curve



Typical values (solid line).

Process limits (dotted line).

WAVE soldering.



IR Reflow Soldering

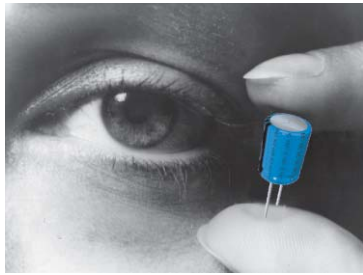
△ Rating

•Lead Free Chip Resistor Array

Type	Size	Power Rating at 70°C	Max. RCWV	Max. Overload Voltage	Resistance Tolerance (%)	Temperature Coefficient (TCR: ppm/°C)	Resistance Range (Ω)		Standard Resistance Values
							Min.	Max.	
RCA 1206	8P4R	1/16W (Element)	50V	100V	±5%(J) ±1%(F)	±200	0Ω, 10Ω	1MΩ	E-24

Jumper: 8P4R size maximum resistance  $R_{max} = 50m\Omega$  and rated current  $I_R = 1A$

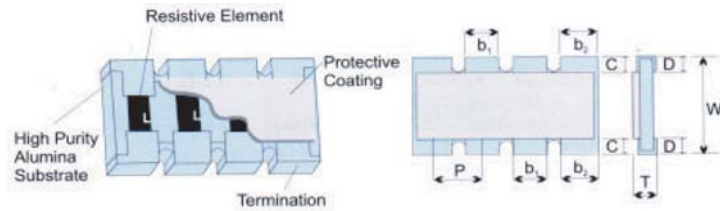
Surface Mount Resistors



### △ Product Category

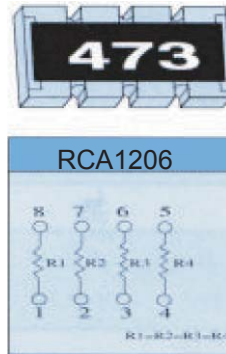
- Lead Free Chip Resistor Array (RCA1206) Convex

### △ Configuration



Inner Termination Layer: Ag, Pd/Ag  
 Middle Termination Layer: Nickel  
 Outer Termination Layer: Solder

### △ Circuit

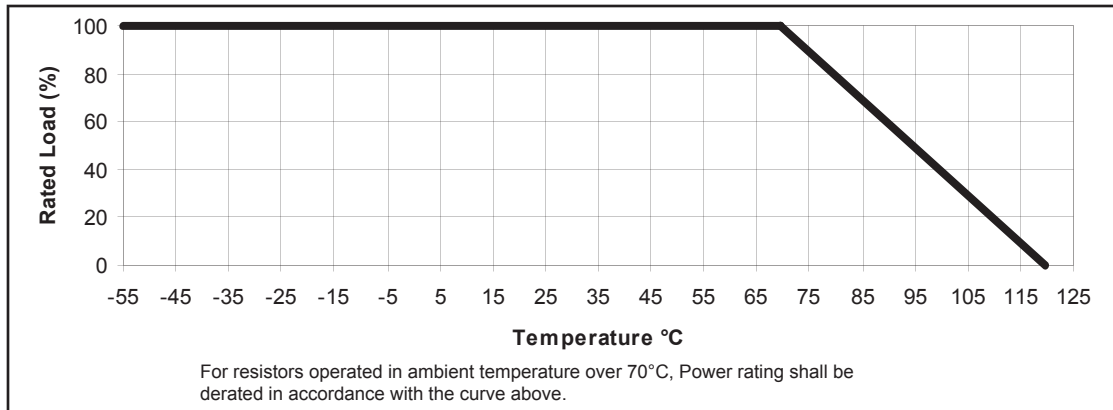


### △ Dimensions

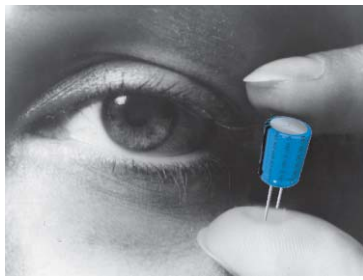
Size	L	W	T	C	D	P	b1	b2
8P4R	3.20±0.20	1.60±0.10	0.50±0.10	0.30±0.20	0.30±0.20	0.80±0.05	0.45±0.10	0.70±0.20

(unit: mm)

### △ Power Derating Curve



Surface Mount Resistors



**△ Product Category**

- Specification and Test Method

ITEM	SPECIFICATION	TEST METHOD
DC Resistance	J: $\pm 5\%$ , F: $\pm 1\%$ Zero Ohm Jumper $< 50\text{m}\Omega$	IEC 115-1 4.5 / JIS C 5202 5.1 Measure the resistance value.
Short Time Overload	J: $\Delta R \leq \pm (2\% + 0.1\Omega)$ F: $\Delta R \leq \pm (1\% + 0.05\Omega)$	IEC 115-1 4.13 / JIS C 5202 5.5 2.5xRated voltage or Max. Overload Voltage for 5 sec. measure resistance after 30 minutes.
Solderability	Over 95% of termination must be covered with solder	IEC 115-1 4.17 / JIS C 5202 6.5 After immersing flux, dip in the $245\pm 2^\circ\text{C}$ molten solder bath for $3\pm 0.5$ sec.
Resistance to Solder Heat	J: $\Delta R \leq \pm (1\% + 0.1\Omega)$ F: $\Delta R \leq \pm (0.5\% + 0.05\Omega)$ No mechanical damage	IEC 115-1 4.18 / JIS C 5202 6.4 with $260\pm 5^\circ\text{C}$ for $10\pm 1$ sec.
Temperature Coefficient of Resistance (TCR)	$\pm 200\text{ppm}/^\circ\text{C}$	IEC 115-1 4.8.4.2 / JIS C 5202 5.2 Test Temperature: $25^\circ\text{C}(T1) \rightarrow -55^\circ\text{C}(T2)$ $25^\circ\text{C}(T1) \rightarrow 125^\circ\text{C}(T2)$ $\text{TCR (ppm}/^\circ\text{C}) = (R2-R1)/R1(T2-T1) \times 10^6$ R1: Resistance at reference temperature (T1) R2: Resistance at test temperature (T2)
Load Life Humidity	J: $\Delta R \leq \pm (3\% + 0.1\Omega)$ F: $\Delta R \leq \pm (1\% + 0.05\Omega)$	IEC 115-1 4.24.2 / JIS C 5202 7.9 Maintain the temperature of the resistor at $40\pm 2^\circ\text{C}$ and 90~95% R.H. with the rated voltage applied. Cycle ON for 1.5 hours. After 1~4 hour, measure the resistance value.
Load Life	J: $\Delta R \leq \pm (3\% + 0.1\Omega)$ F: $\Delta R \leq \pm (1\% + 0.05\Omega)$	IEC 115-1 4.25.1 / JIS C 5202 7.10 Permanent resistance change after 1000+48/-0 hours (1.5 hours ON, 0.5 hour OFF) at RCWV or MAX. Keep the resistor at $70\pm 2^\circ\text{C}$ ambient
Intermittent Overload	$\Delta R \leq \pm (3\% + 0.1\Omega)$ No mechanical damage	JIS C 5202 5.8 4.0xRated voltage (Max. Overload Voltage) 1 sec ON, 25 sec OFF, test 10,000 cycles
Temperature Cycle	J: $\Delta R \leq \pm (1\% + 0.1\Omega)$ F: $\Delta R \leq \pm (0.5\% + 0.05\Omega)$ No mechanical damage	IEC 115-1 4.19 / JIS C 5202 7.4 Repeat 5 cycles as follows $-55^\circ\text{C}$ (30min) $+25^\circ\text{C}$ (2~3min) $+125^\circ\text{C}$ (30min) $+25^\circ\text{C}$ (2~3min)
Insulation Resistance	Between termination and coating must be over $1000\text{M}\Omega$	IEC 115-1 4.6.1.1 / JIS C 5202 5.6 Test voltage: $100\pm 15\text{V}$
Bending Strength	J: $\Delta R \leq \pm (1\% + 0.1\Omega)$ F: $\Delta R \leq \pm (0.5\% + 0.05\Omega)$ No mechanical damage	IEC 115-1 4.33 Resistance change after bended on the 90mm PCB. Bend: 3min